

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com





Naturally, the CH20M system also shows its perfection in the peripheral interface.

If you are taking into consideration design options, processing, usability, reliability and security, then pin headers and connectors are just as critical in the real world as the entire system.

In every sector, the connection technology is at the top of its class.

- **100% non-interchangeable** the unique, captive "Auto-Set" encoding ensures a misconnection-proof assignment of the connections.
- **100% safe** Touch protection for the pin header and socket block on both sides
- **100% efficient** All THR pin headers are reflow compatible

General ordering data

Туре	SHL-SMT 5.00/02GL 1.5BX	
Order No.	1069620000	
Version PCB plug-in connector, Connection ele left, male header, open side, THT/THR connection, 5.00 mm, Number of pole Solder pin length (I): 1.5 mm, tinned, b		
GTIN (EAN)	4032248825158	
Qty.	150 pc(s).	
Product data	IEC: 400 V UL: 300 V / 9 A / AWG 26 - AWG 12	
Packaging	Box	

Technical data

Dimensions and weights



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Length	22 mm	Length (inches)	0.866 inch
Width	10.4 mm	Width (inches)	0.409 inch
Height	14.4 mm	Height (inches)	0.567 inch
Net weight	1.85 g		
System specifications			
Product family	OMNIMATE Housing -	Type of connection	
	series CH20M		Board connection
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)	
	connection		5 mm
Pitch in inches (P)	0.197 inch	Outgoing elbow	90°
Number of poles	2	Number of solder pins per pole	1
Solder pin length (I)	1.5 mm	Solder pin length tolerance	+0.1 / -0.2 mm
Tolerance of solder pin position	± 0.1 mm	L1 in mm	5 mm
L1 in inches	0.197 inch	Number of rows	1
Pin series quantity	1	Volume resistance	≤ 5mΩ
			25

Material data

Insulating material	LCP
Colour chart (similar)	RAL 9011
Comparative Tracking Index (CTI)	≥ 175
Moisture Level (MSL)	1
Contact material	Copper alloy
Storage temperature, min.	-25 °C
Max. relative humidity during storage	70 %
Operating temperature, max.	120 °C
Temperature range, installation, max.	120 °C

Colour	black
Insulating material group	Illa
Insulation strength	≥ 10 ⁸ Ω
UL 94 flammability rating	V-0
Contact surface	tinned
Storage temperature, max.	50 °C
Operating temperature, min.	-40 °C
Temperature range, installation, min.	-30 °C

Rated data acc. to IEC

IEC 60664-1, IEC 61984
9 A
320 V
4 kV
4 kV

Rated current, max. number of poles (Tu=20°C)	10 A
Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/3 250 V	
Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV

Technical data

Rated data acc. to CSA

Institute (CSA)



Rated voltage (Use group B / CSA)	300 V
Rated voltage (Use group D / CSA)	300 V
Rated current (Use group C / CSA)	9 A
Wire cross-section, AWG, min.	AWG 26
Reference to approval values	Specifications are maximum values, details - see approval certificate

Rated data acc. to UL 1059

Institute (cURus)



Rated voltage (Use group B / UL 1059)	300 V
Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group C / UL 1059)	9 A
Wire cross-section, AWG, min.	AWG 26
Reference to approval values	Specifications are maximum values, details - see approval certificate.

Certificate No. (cURus)

Certificate No. (CSA)

Rated voltage (Use group C / CSA)

Rated current (Use group B / CSA)

Rated current (Use group D / CSA)

Wire cross-section, AWG, max.

	E60693
Rated voltage (Use group C / UL 1059)	50 V
Rated current (Use group B / UL 1059)	9 A
Rated current (Use group D / UL 1059)	9 A
Wire cross-section, AWG, max.	AWG 12

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02
eClass 10.0	27-44-04-02		

Notes

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Approvals

Approvals



ROHS

Conform

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200039-70153051

50 V

9 A

9 A

AWG 12

Technical data

Downloads

Approval/Certificate/Document	of
Conformity	CSA Certificate of Compliance
Brochure/Catalogue	FL ANALO.SIGN.CONV. EN
	MB DEVICE MANUF. EN
	CAT 2 PORTFOLIOGUIDE EN
	FL MACHINE SAFETY EN
	FL 72H SAMPLE SER EN
	PO OMNIMATE EN
Engineering Data	STEP



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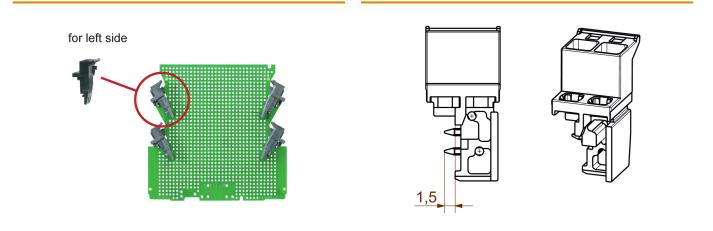
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Drawings



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delivery

Creation date May 1, 2020 3:42:37 PM CEST

Catalogue status 17.04.2020 / We reserve the right to make technical changes.

Reflow Solder Profile

Recommended reflow soldering profile



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Time [sec]

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.

Wave Solder Profile

Recommended wave solderding profiles

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Double Wave:

Single Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

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